



# UTD484

*Power MOSFET*

## N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

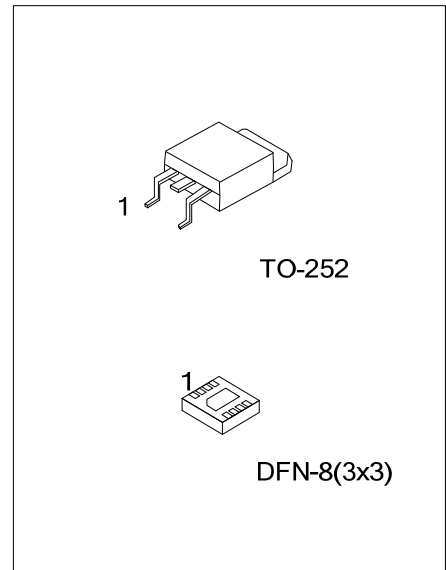
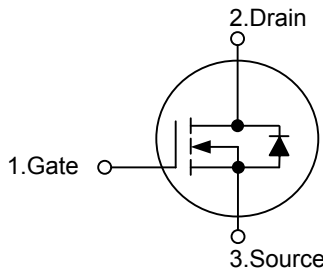
### DESCRIPTION

The **UTD484** uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

### FEATURES

- \*  $R_{DS(ON)} < 15m\Omega @ V_{GS} = 10V, I_D = 20A$
- \* Low capacitance
- \* Low gate charge
- \* Fast switching capability
- \* Avalanche energy specified

### SYMBOL



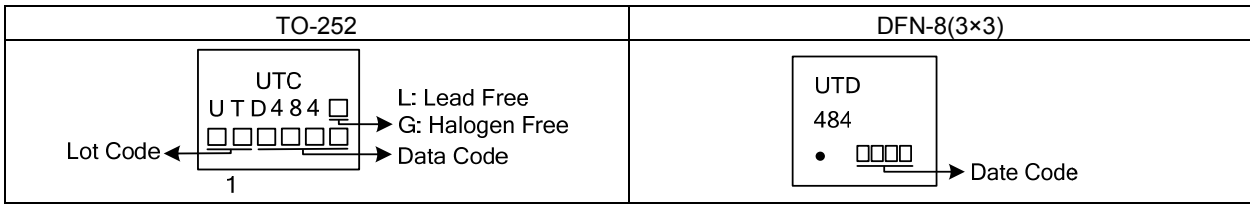
### ORDERING INFORMATION

Ordering Number		Package	Pin Assignment								Packing
Lead Free	Halogen Free		1	2	3	4	5	6	7	8	
UTD484L-TN3-T	UTD484G-TN3-T	TO-252	G	D	S	-	-	-	-	-	Tube
UTD484L-TN3-R	UTD484G-TN3-R	TO-252	G	D	S	-	-	-	-	-	Tape Reel
-	UTD484G-K08-3030-R	DFN-8(3x3)	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>UTD484L-TN3-R</p> <p>(1)Packing Type</p> <p>(2)Package Type</p> <p>(3)Green Package</p>	<p>(1) R: Tape Reel</p> <p>(2) TN3: TO-252, K08-3030: DFN8(3x3)</p> <p>(3) L: Lead Free, G: Halogen Free and Lead Free</p>
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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	30	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	25	A
Pulsed Drain Current(Note 1)		$I_{DM}$	80	A
Avalanche Current(Note 1)		$I_{AR}$	15	A
Repetitive avalanche energy $L=0.3\text{mH}$ (Note 1)		$E_{AR}$	33	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	TO-252 DFN-8(3x3)	41	W
	$T_A = 25^\circ\text{C}$	TO-252	2.1	
		DFN-8(3x3) (Notes 3)	1.9	
Junction Temperature		$T_J$	+150	$^\circ\text{C}$
Storage Temperature		$T_{STG}$	-55 ~ +175	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Pulse width limited by  $T_{J(MAX)}$

3. Exposed pad is ground and must be soldered to PCB

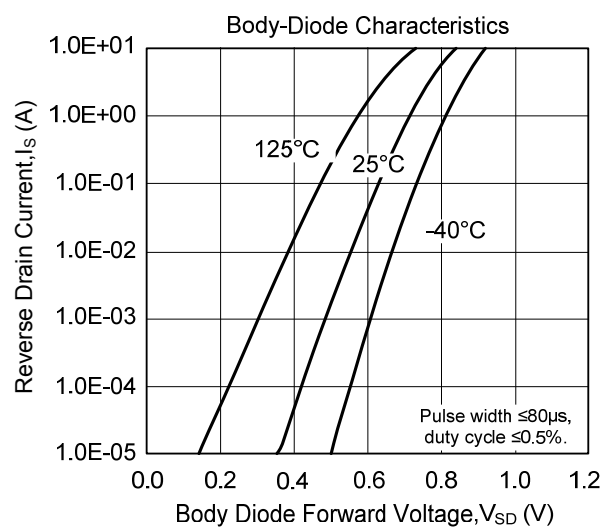
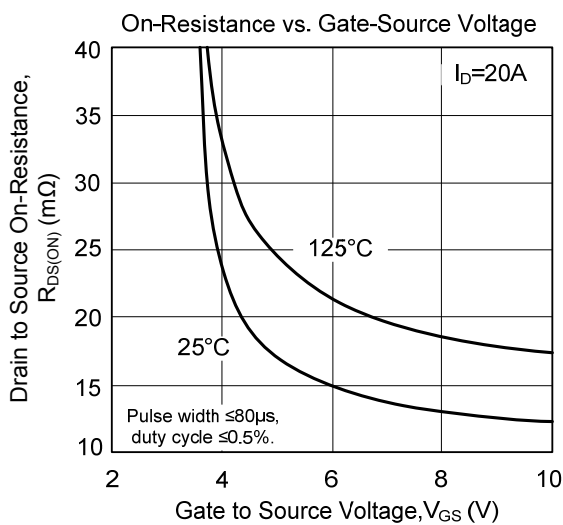
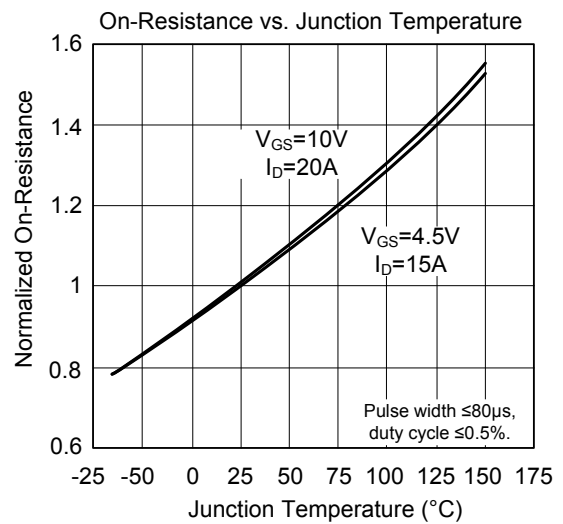
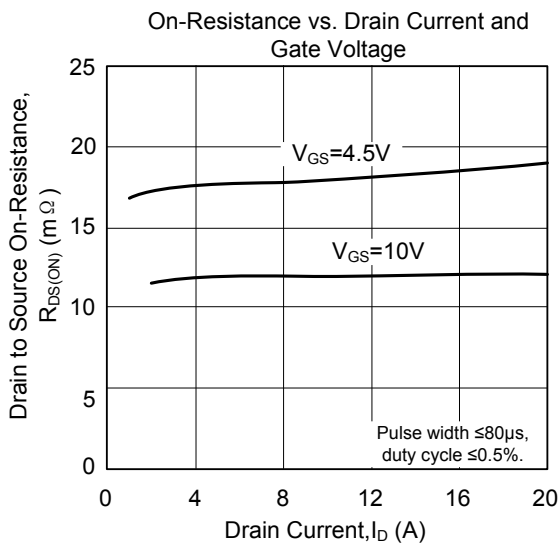
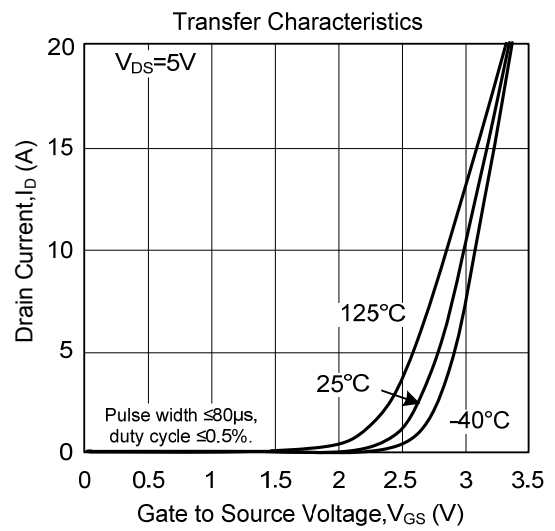
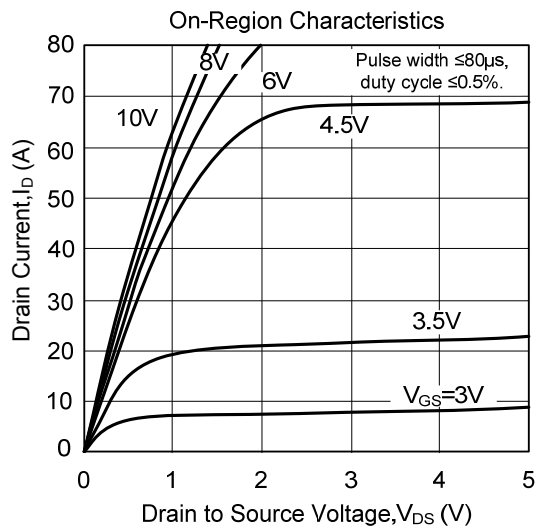
■ THERMAL DATA

PARAMETER		SYMBOL	MIN	TYP	MAX	UNIT
Junction-to-Ambient	TO-252	$\theta_{JA}$		55	60	$^\circ\text{C/W}$
	DFN-8(3x3)				65	$^\circ\text{C/W}$
Junction-to-Case	TO-252/DFN-8(3x3)	$\theta_{JC}$		2.3	3	$^\circ\text{C/W}$

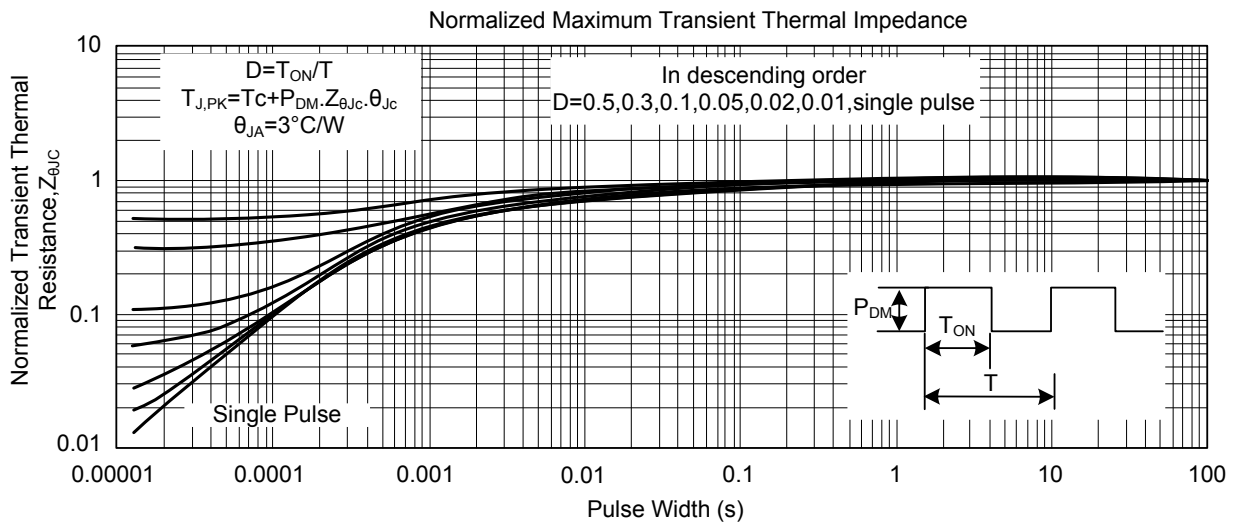
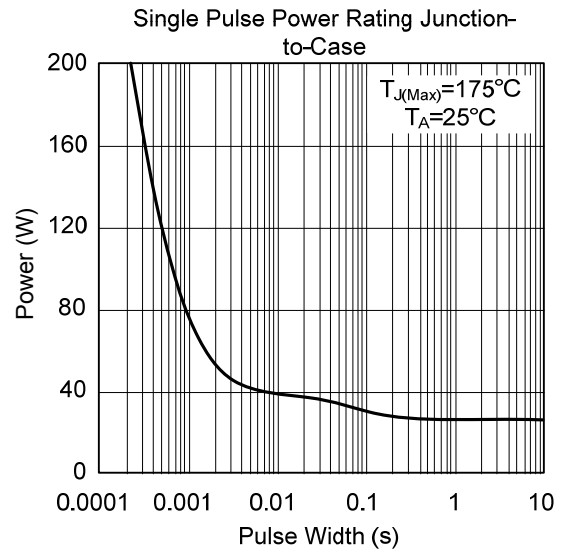
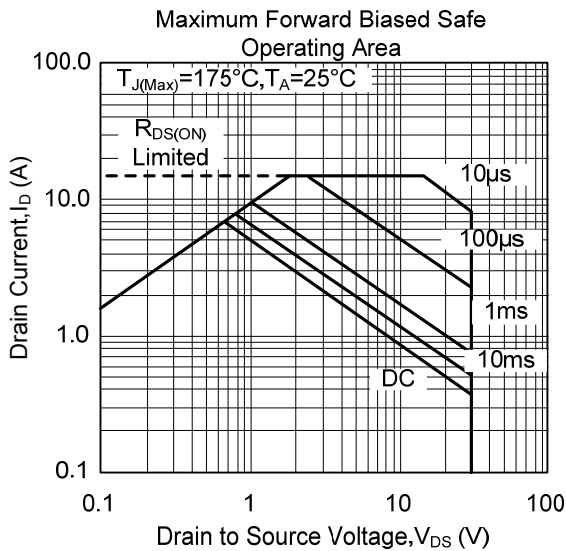
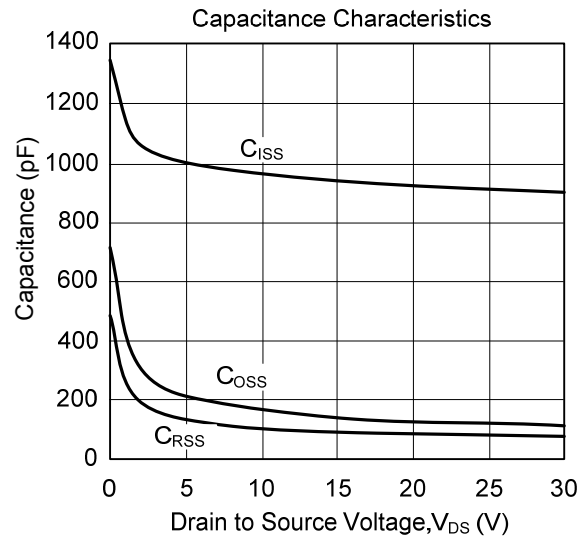
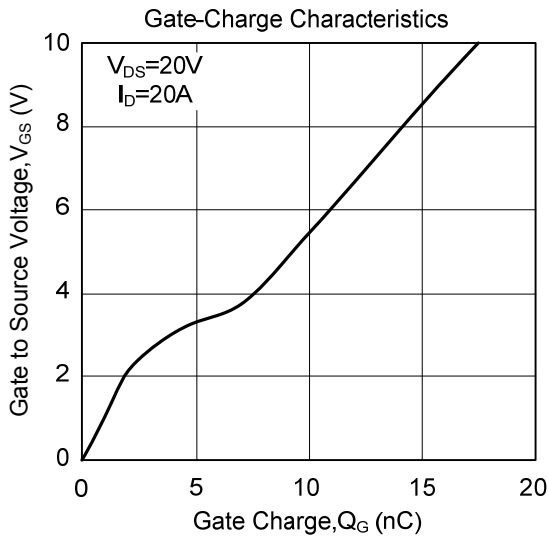
■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub> =25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	30			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0 V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0 V, V <sub>GS</sub> = ±20V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1	1.5	2.5	V
On State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> =5 V, V <sub>GS</sub> =10V	80			A
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =20 A		12.1	15	mΩ
		V <sub>GS</sub> =4.5 V, I <sub>D</sub> =15 A		18.5	23	
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =15 V, V <sub>GS</sub> =0V, f=1MHz		938	1220	pF
Output Capacitance	C <sub>OSS</sub>			142		
Reverse Transfer Capacitance	C <sub>RSS</sub>			99		
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge	Q <sub>G</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =20 A		17.5	21	nC
Gate Source Charge	Q <sub>GS</sub>			3		
Gate Drain Charge	Q <sub>GD</sub>			4.1		
Turn-ON Delay Time	t <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =0.75Ω, R <sub>GEN</sub> =3Ω		5		ns
Turn-ON Rise Time	t <sub>R</sub>			12		
Turn-OFF Delay Time	t <sub>D(OFF)</sub>			19		
Turn-OFF Fall-Time	t <sub>F</sub>			6		
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.71	1	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				21	A
Body Diode Reverse Recovery Time	t <sub>RR</sub>	I <sub>F</sub> =20 A, dI/dt=100A/μs		19	21	ns
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>				10	12

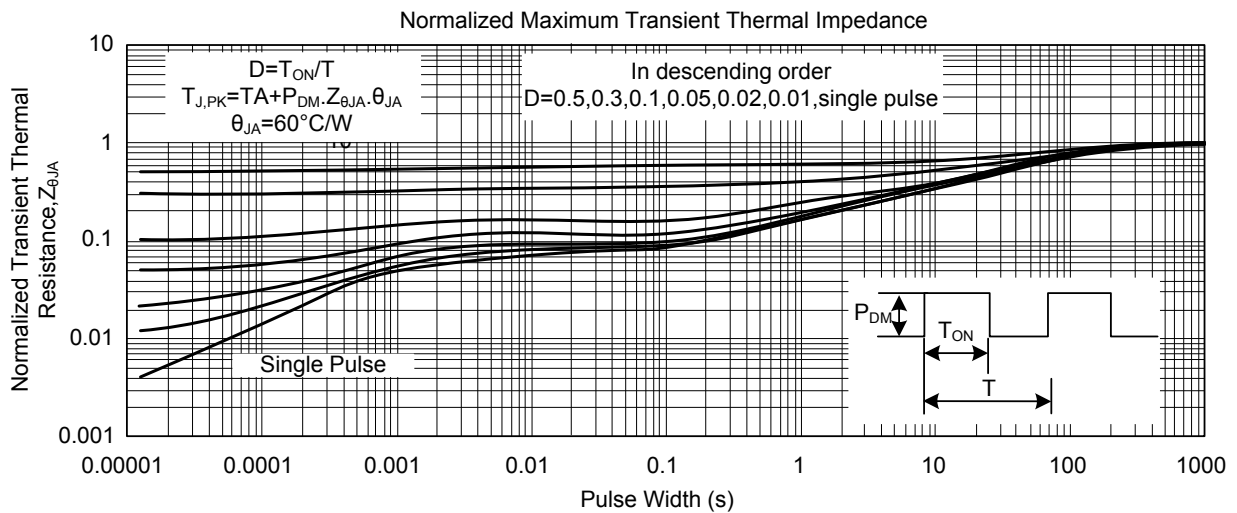
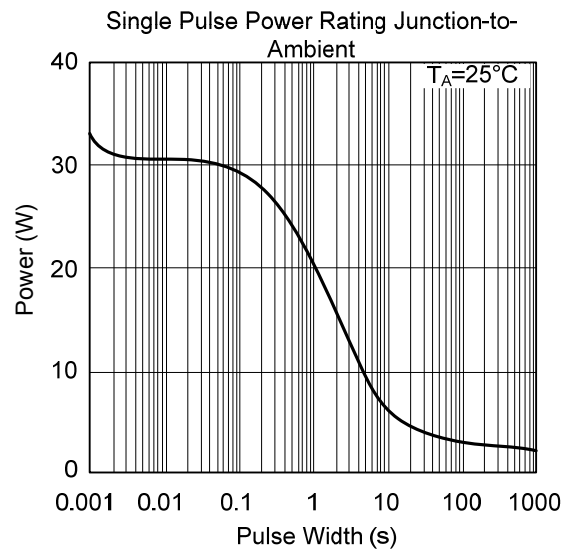
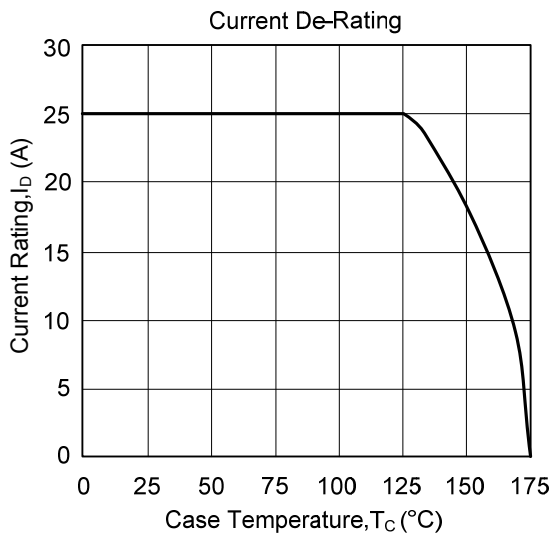
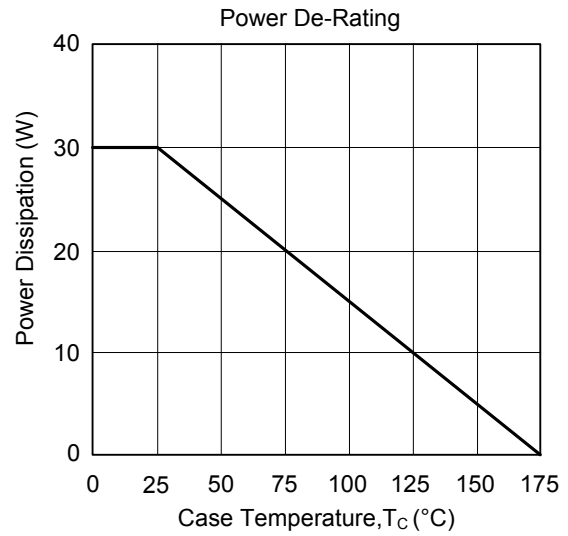
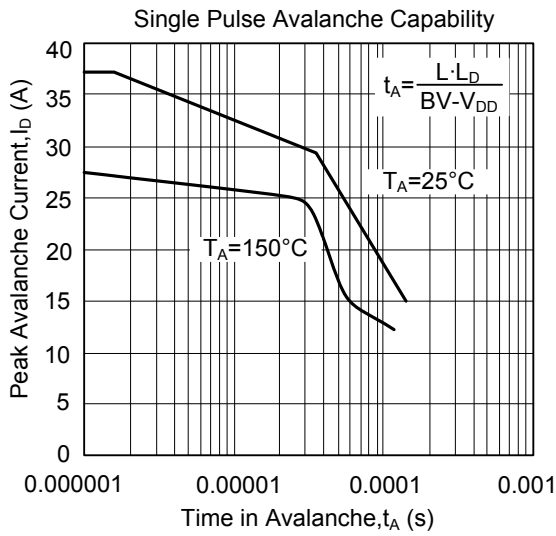
## TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS(Cont.)



## ■ TYPICAL CHARACTERISTICS(Cont.)



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